



photonics

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Advances in Optical 3D Integration

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Message from the Guest Editor

Optical 3D integration is becoming a growing trend in photonic integrated circuits, similar to what we have observed in electronic integrated circuit development. It not only offers high degrees of integration but also bringing new functionalities to microsystems. Combining with nanoelectronics, 3D integrated photonics would enable novel applications in sensing, high-performance computing, light detection and ranging (LiDAR), artificial intelligence, etc.

In this special issue, we will discuss emerging technologies and applications in optical 3D integration. We welcome you to submit your work in form of reviews, articles and communications. Topics of interest include but are not limited to:

- Multilayer stacked photonic integrated circuits;
- 3D arbitrary photonics by ultrafast laser inscription;
- 3D printing for photonic integration;
- Novel fabrication process for optical 3D integration;
- Advanced 3D packaging techniques for electronic-photonic integration;
- Novel applications enabled by 3D electronic-photonic integrated circuits;



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Special Issue